

ABSTRACT

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METHOD FOR DRYING RESIN-USED ELECTRONIC PARTS

Provided is a method for drying resin-used electronic parts which comprises enclosing resin-used electronic parts together with both an oxygen absorbent requiring no moisture for absorption of oxygen and a drying agent in a container having a gas barrier property and then sealing the container and removing oxygen and, preferably, then heating the sealed container. Thereby, no quality deterioration due to oxidation and degradation of a metal surface occurs in a drying step of resin-used electronic parts.